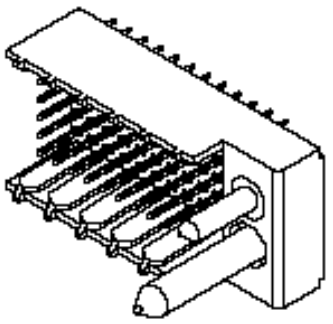
This document was generated on 05/14/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0736440106
Status: Active
Overview: hdm
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location B, Polarizing Key Position D, 72 Circuits



Series image - Reference only

Documents:
Drawing (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	Yes
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05
Polarized to PCB	No

EU RoHS | **China RoHS**
Compliance Status
Not Reviewed
REACH SVHC
Not Reviewed
Halogen-Free Status
Not Reviewed

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
73644Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | **FAQ**
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Flat Rock Tooling for Pneumatic Press	0622013700
HDM® Backplane Insertion Signal Contact Tool	0621001400
Extraction Tool	0621001000

Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

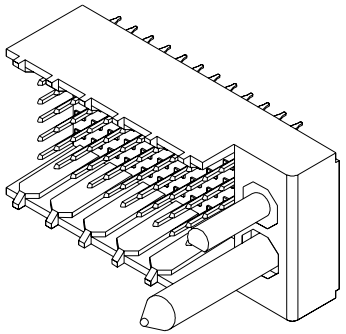
Reference - Drawing Numbers

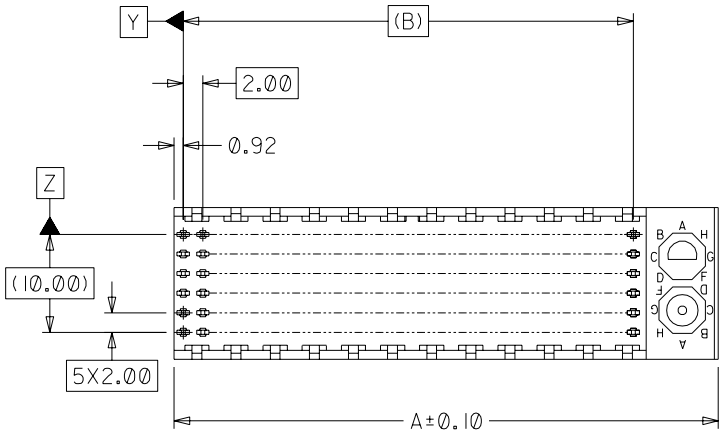
Packaging Specification	PK-70873-0818
Sales Drawing	SDA-73644-****

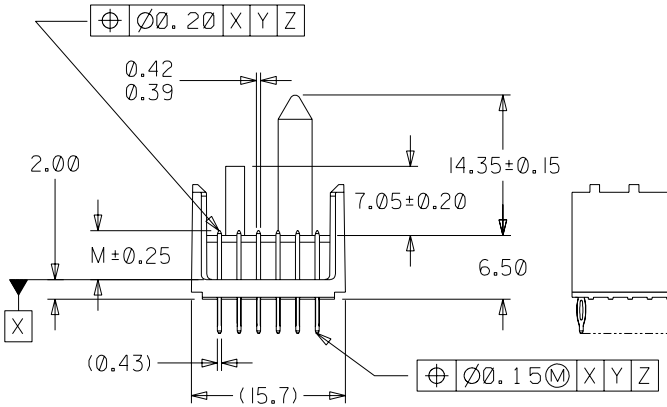
HDM and High Density Metric are trademarks of Amphenol Corporation

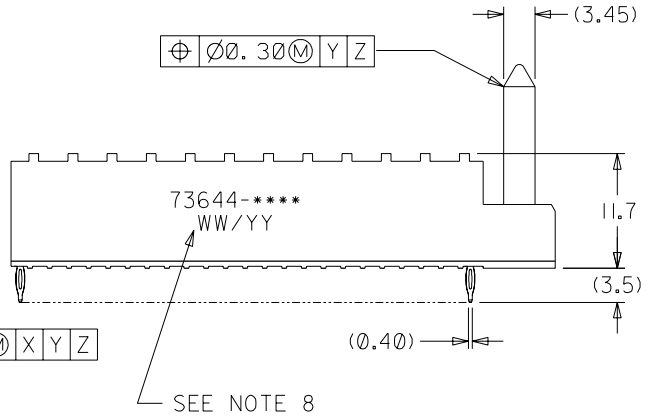
NOTES:

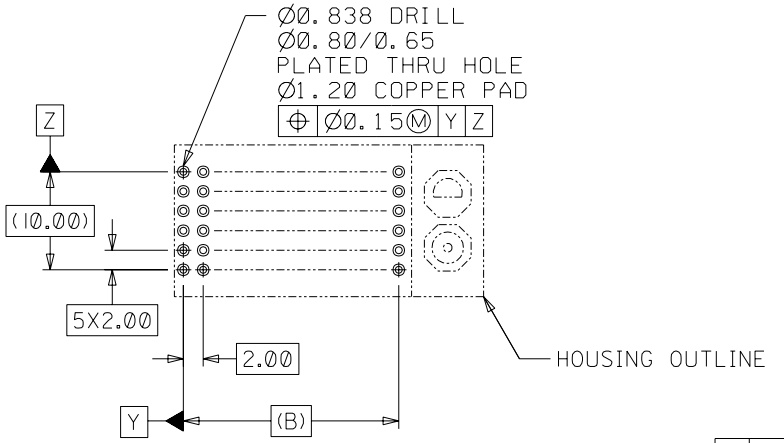
1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK,
   TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL
   SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MIN. THICKNESS; SELECTIVE TIN/LEAD (Sb/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. DIMENSIONS ARE IN MILLIMETERS.
6. FOR SPECIFIC MATERIAL NUMBERS, REFER TO SHEET 2.
7. PACKAGE PER PK-70873-0818.
8. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.











PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

2	D
1	J

MFG. SH. REV.

LTR.	REVISIONS	LTR.	REVISIONS
		I	REVISED ECR UDT2000-0348 BINGHAM 99/10/12
		H	REVISED ECR UDT1999-0662 BINGHAM 99/05/18
J	REVISED ECR UCP2003-2260 THOMAS 03/04/25	G	REVISED ECR UDT1999-0476 BINGHAM 98/12/21

DIMENSIONS SHOWN (METRIC) INCH
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°

	INCH	METRIC
3 PLACE	± N/A	---
2 PLACE	± N/A	± 0.05
1 PLACE	---	± 0.10

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DRWG. BY	JRR	CHK'D. BY	SMR
APP'D. BY	CAB	SCALE	2 : 1

C = 0 ▼ = 0 REVISE ONLY ON CAD SYSTEM

TITLE
SALES ASSY, HDM BACKPLANE MODULE, POLAR/GUIDE OPTION

molex MOLEX INCORPORATED LISLE,ILL. 60532 U.S.A.

SHEET NO. 1 OF 2

DATE 96/12/18

PART NO. SEE CHART

DRWG. NO. SDA-73644-****

FILE NAME S73644X1 DGN

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

DIV. DA SIZE B

MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	PLATING	DIM "A"	DIM "B"	DIM "M"
73644-00**	72	SELECTIVE GOLD/GOLD FLASH	31.60	22.00	5.00
73644-01**	72	SELECTIVE GOLD/GOLD FLASH	31.60	22.00	5.50
73644-02**	72	SELECTIVE GOLD/GOLD FLASH	31.60	22.00	6.00
73644-10**	144	SELECTIVE GOLD/GOLD FLASH	55.60	46.00	5.00
73644-11**	144	SELECTIVE GOLD/GOLD FLASH	55.60	46.00	5.50
73644-12**	144	SELECTIVE GOLD/GOLD FLASH	55.60	46.00	6.00
73644-20**	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	31.60	22.00	5.00
73644-21**	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	31.60	22.00	5.50
73644-22**	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	31.60	22.00	6.00
73644-30**	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	55.60	46.00	5.00
73644-31**	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	55.60	46.00	5.50
73644-32**	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	55.60	46.00	6.00

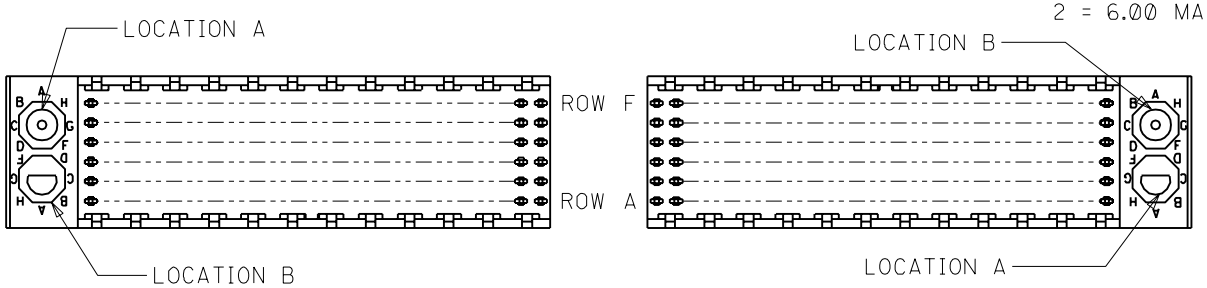
MATERIAL NUMBER ASSIGNMENT

73644- * * * *

0 = 72-CIRCUIT, GOLD/GOLD FLASH
1 = 144-CIRCUIT, GOLD/GOLD FLASH
2 = 72-CIRCUIT, GOLD/TIN-LEAD
3 = 144-CIRCUIT, GOLD/TIN-LEAD

0 = 5.00 MATING LENGTH
1 = 5.50 MATING LENGTH
2 = 6.00 MATING LENGTH

NUMBER	GUIDE POST LOCATION	POLAR KEY POSITION
00	B	A
01	A	
02	B	B
03	A	
04	B	C
05	A	
06	B	D
07	A	
08	B	E
09	A	
10	B	F
11	A	
12	B	G
13	A	
14	B	H
15	A	
16	B	N/A
17	A	
18	N/A	



REF. MATERIAL NUMBER 73644-0009
GUIDE PIN IS IN LOCATION A
POLARIZING KEY IS IN LOCATION B, POSITION E

REF. MATERIAL NUMBER 73644-0008
GUIDE PIN IS IN LOCATION B
POLARIZING KEY IS IN LOCATION A, POSITION E

LTR.	REVISIONS	LTR.	REVISIONS
		D	SEE SHEET 1

DIMENSIONS SHOWN (METRIC) INCH
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°

	INCH	METRIC
3 PLACE	± N/A	---
2 PLACE	± N/A	± N/A
1 PLACE	---	± N/A

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DRWG. BY	JRR	CHK'D. BY	SMR
APP'D. BY	CAB	SCALE	--:--

C = 0 ▼ = 0 REVISE ONLY ON CAD SYSTEM

TITLE
SALES ASSY, HDM BACKPLANE MODULE, POLAR/GUIDE OPTION

MOLEX INCORPORATED
LISLE, ILL. 60532 U.S.A.

SHEET NO. 2
DATE 96/12/18

PART NO. SEE CHART
DRWG. NO. SDA-73644-****

FILE NAME S73644X2 DGN

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DIV. DA
SIZE B

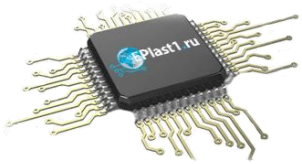
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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